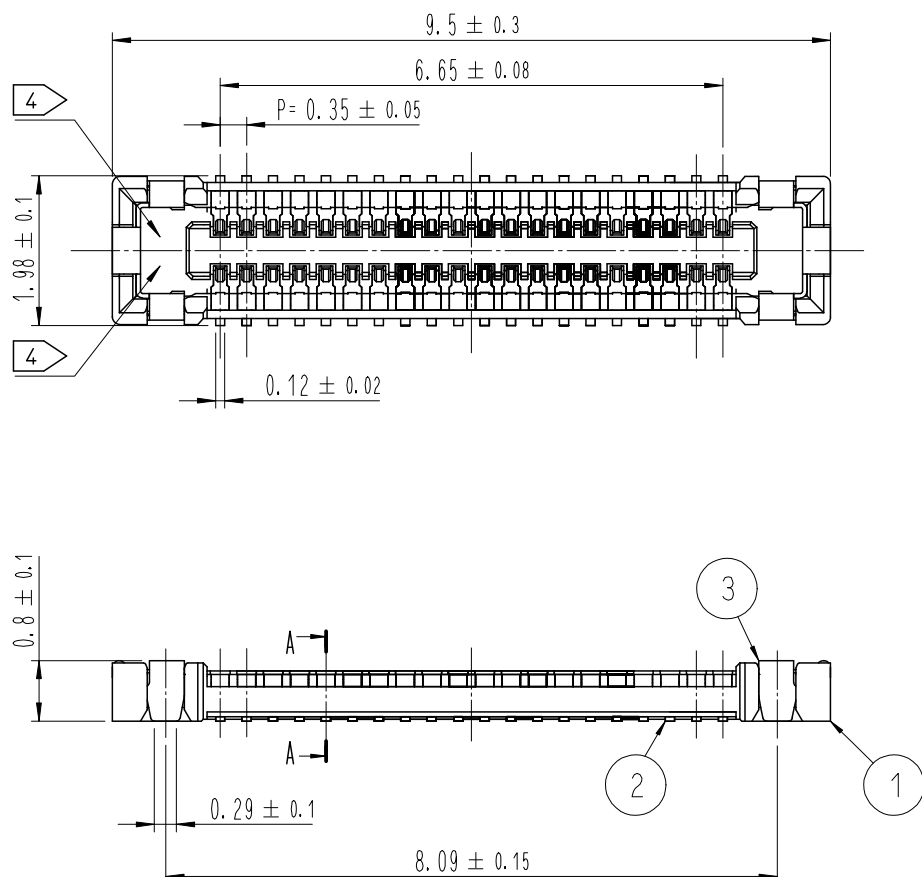


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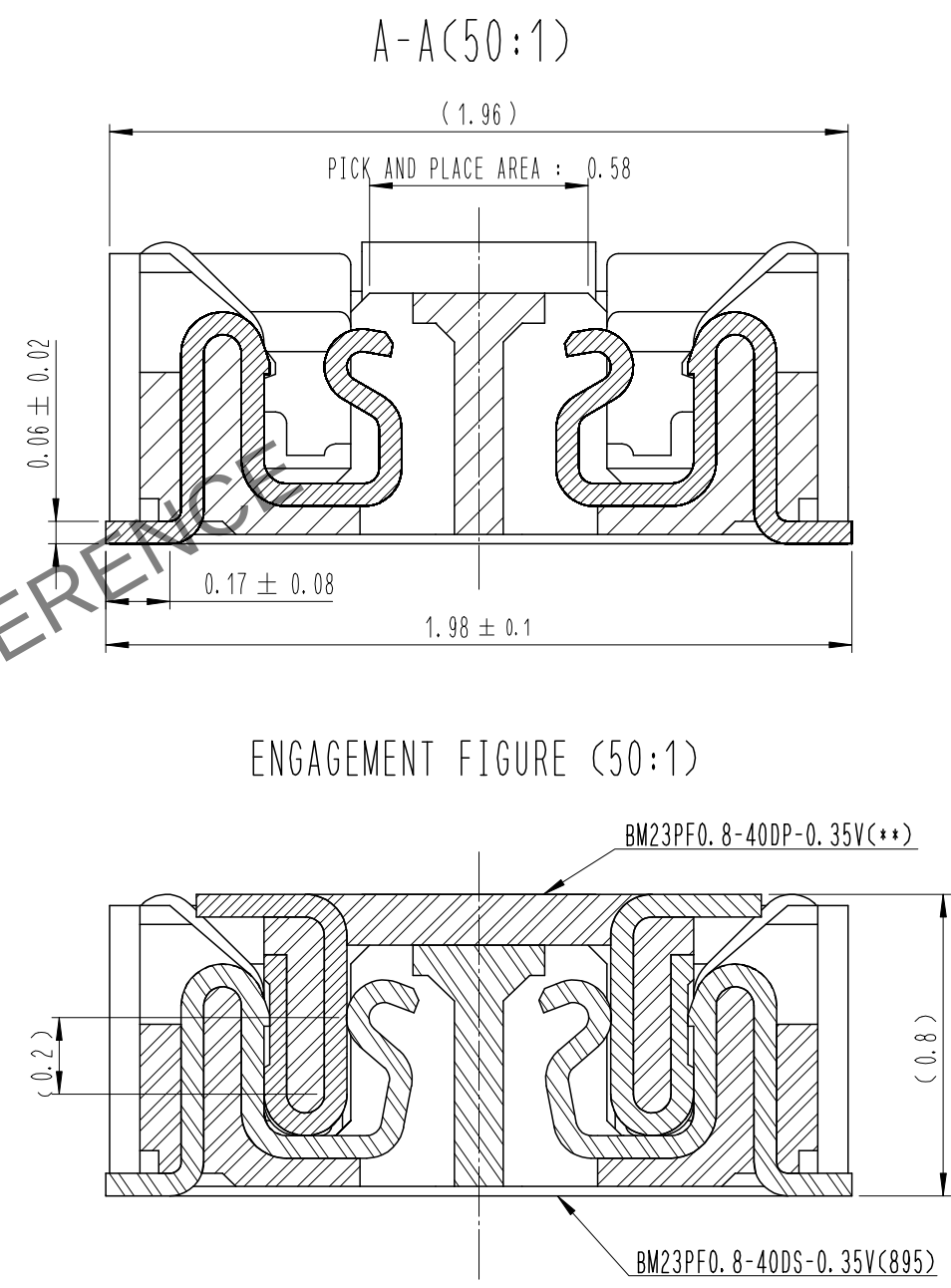
A
B
C
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E
F



DRAWING FOR REFERENCE
This is subject to change without notice

- NOTE
- 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX.
 - 2. CONTACT PLATING SPECIFICATIONS.
CONTACT AREA : GOLD 0.05 μm MIN.
SMT LEAD : GOLD 0.05 μm MIN.
UNDERPLATING : NICKEL 1 μm MIN.
(SURFACE : SEALING)
 - 3. MATAL FITTING PLATING SPECIFICATIONS.
SMT LEAD : GOLD 0.05 μm MIN.
UNDERPLATING : NICKEL 1 μm MIN.
(SURFACE : SEALING)
 - 4. HRS MARK AND CAV NO. IS INDICATED IN APPROX POSITION SHOWN.

5		6			7		8		
△數	訂正事項	擔當	檢圖	年月日	△數	訂正事項	擔當	檢圖	年月日
COUNT	DESCRIPTION OF REVISIONS	B	Y	CHKD	DATE	DESCRIPTION OF REVISIONS	B	Y	CHKD
△									
△									
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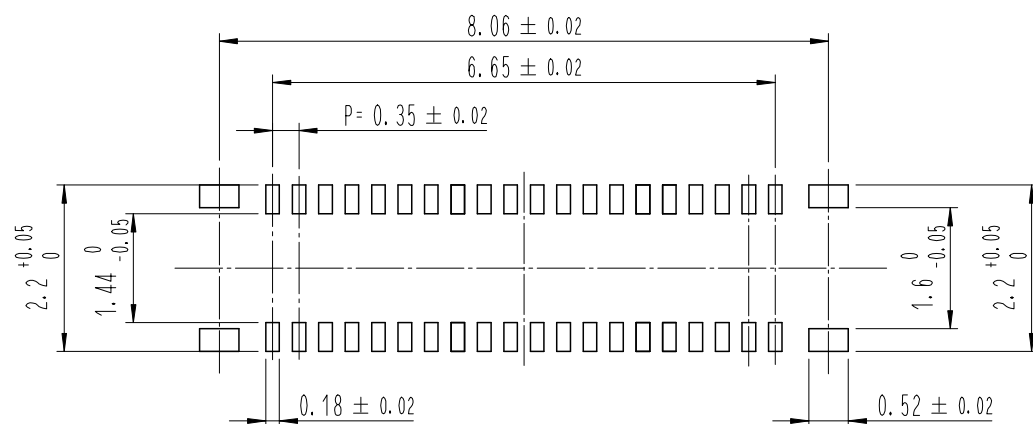


4	PS	CLEAR (EMBOSSED CARRIER TAPE)			
3	COPPER ALLOY	3			
2	COPPER ALLOY	2	6	PS	BLACK (PLASTIC REEL)
1	LCP	UL94 V-0, BLACK	5	POLYESTER	CLEAR (COVER TAPE)
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS
REMARKS			DRAWN	DESIGNED	CHECKED
			S. H. JUNG	S. H. JUNG	H. W. JO
			17. 05. 09	17. 05. 09	17. 05. 09
				APPROVED	RELEASED
				T. S. KANG	17. 05. 09
CODE NO. (OLD)	SCALE	DRAWING NO.	PART NO.		
	10:1	EDC3-631971	BM23PF0.8-40DS-0.35V(895)		
	UNITS	HIROSE KOREA CO., LTD.	CODE NO		
	mm		CL 6644-0047-8-895		
					1/3

A
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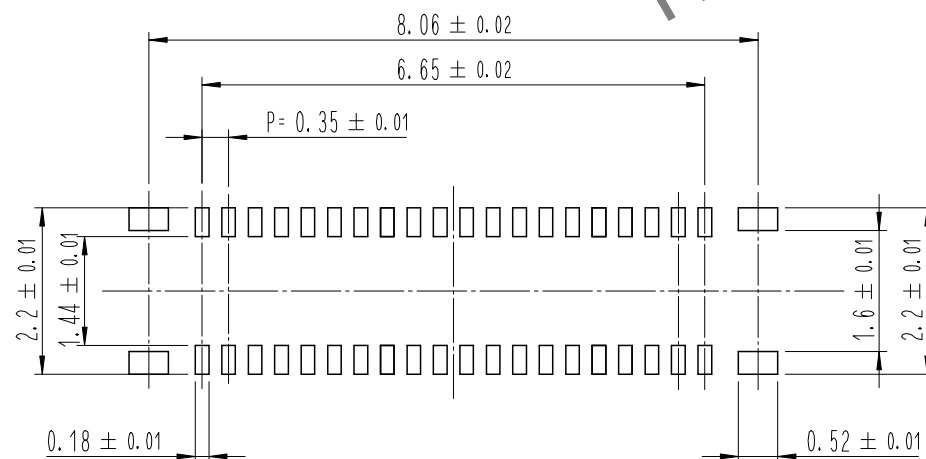
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6 RECOMMENDED PCB LAYOUT

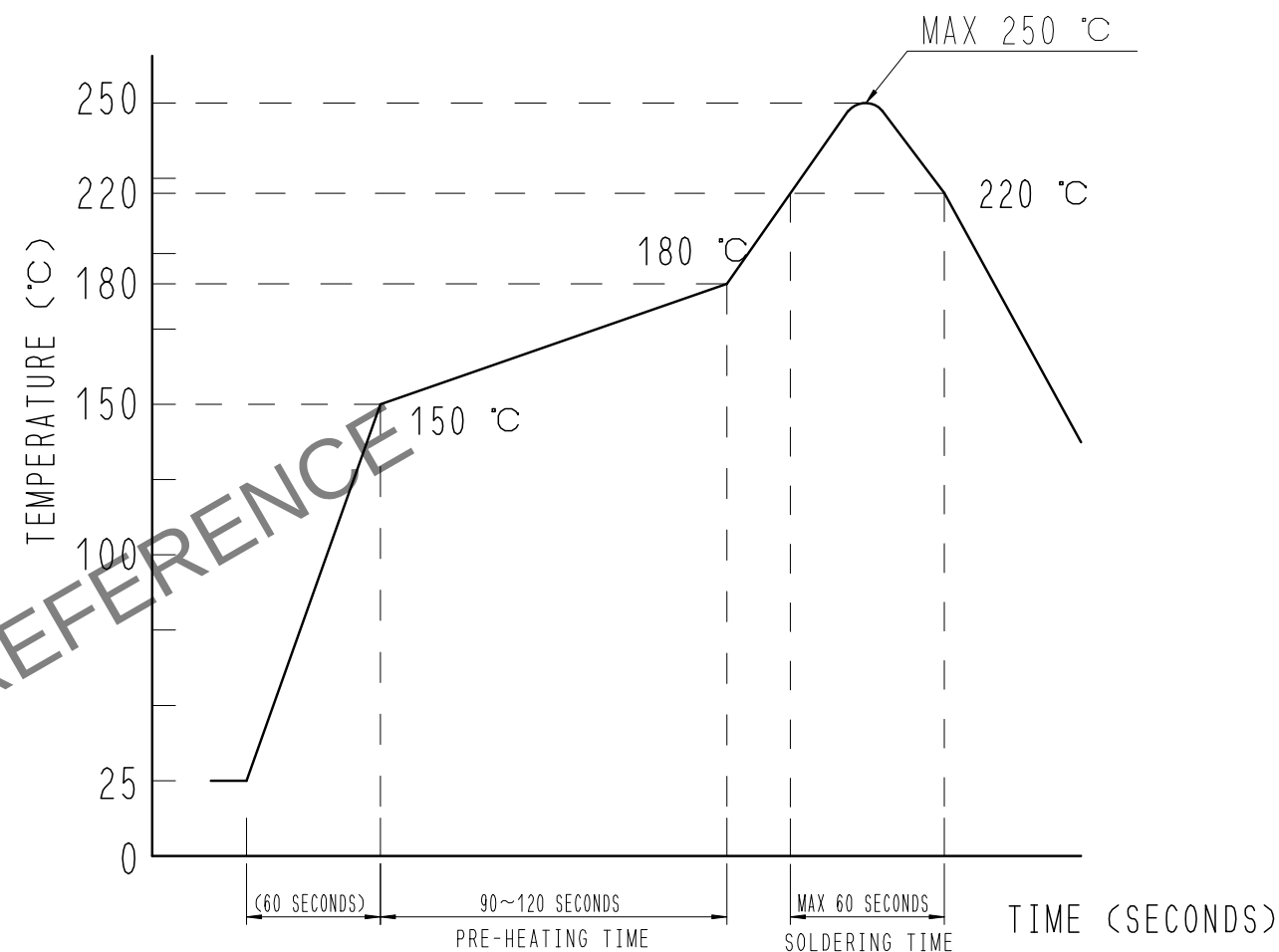


 RECOMMENDED METAL MASK DIMENSIONS

MATAL MASK THICKNESS : $100 \mu\text{m}$



5 RECOMMENDED REFLOW TEMPERATURE PROFILE
USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: N2 REFLOW

NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.

1) REFLOW TIME

DURATION ABOVE 220 $^{\circ}\text{C}$: 60 SEC MAX.

(PEAK TEMPERATURE: 250 $^{\circ}\text{C}$ MAX)

2) PRE-HEAT TIME

PRE-HEAT TEMPERATURE (MIN): 150 $^{\circ}\text{C}$

PRE-HEAT TEMPERATURE (MAX): 180 $^{\circ}\text{C}$

PRE-HEAT TIME: 90~120 SEC.

5  THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE.
ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND
OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE,
A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED
PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

6  PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.

	DRAWING NO. EDC3-631971		PART NO. BM23PF0.8-40DS-0.35V(895)	
SCALE 10:1	 HIROSE KOREA CO., LTD.		CODE NO	
UNITS mm			CL 6644-0047-8-895	
			2/3	

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